

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5538	((29/846,847,850,852,853) or (174/262)).CCLS.	US-PGPUB; USPAT	OR	OFF	2008/09/29 14:36
L2	237	l1 and @pd> "20080501"	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/29 14:36
S1	1	("6407345").PN.	US-PGPUB; USPAT	OR	OFF	2008/09/26 16:15
S2	88	(printed circuit or circuit board or pcb or wiring board or printed board) and substrate same3 hole same3 (plated or plating or electroless or electroplating or electroplated) same3 (lacquer)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/26 16:43
S3	4	(printed circuit or circuit board or pcb or wiring board or printed board) and substrate same3 hole same (plated or plating or electroless or electroplating or electroplated) and (lacquer) with (printed circuit or circuit board or pcb or wiring board or printed board) and hole with (filled or filling)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/26 17:00
S4	5597	(printed circuit or circuit board or pcb or wiring board or printed board) and hole same (plated or plating or electroless or electroplating or electroplated) and hole with (filled or filling)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/26 17:22
S5	2967	(printed circuit or circuit board or pcb or wiring board or printed board) and substrate same3 hole same (plated or plating or electroless or electroplating or electroplated) and hole with (filled or filling)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/26 17:22
S6	1318	(printed circuit or circuit board or pcb or wiring board or printed board) and substrate same3 hole same (plated or plating or electroless or electroplating or electroplated) and hole with (filled or filling) with (lacquer or insulating or insulator or dielectric or resin)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/26 17:35

S7	929	(printed circuit or circuit board or pcb or wiring board or printed board) and substrate same3 hole same (plated or plating or electroless or electroplating or electroplated) and hole near5 (filled or filling) near5 (lacquer or insulating or insulator or dielectric or resin)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/26 17:36
S8	869	(printed circuit or circuit board or pcb or wiring board or printed board) and substrate same hole same (plated or plating or electroless or electroplating or electroplated) and hole near5 (filled or filling) near5 (lacquer or insulating or insulator or dielectric or resin)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/26 17:37
S9	576	(printed circuit or circuit board or pcb or wiring board or printed board).ti,ab, cdm. and substrate same3 hole same (plated or plating or electroless or electroplating or electroplated) and hole near5 (filled or filling) near5 (lacquer or insulating or insulator or dielectric or resin)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/26 17:38
S10	828	(printed circuit or circuit board or pcb or wiring board or printed board) and (etched or etching or etchant) and substrate same3 hole same (plated or plating or electroless or electroplating or electroplated) and hole near5 (filled or filling) near5 (lacquer or insulating or insulator or dielectric or resin)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/26 17:39
S11	980	(printed circuit or circuit board or pcb or wiring board or printed board) and (etched or etching or etchant) and substrate same3 hole with (plated or plating or electroless or electroplating or electroplated) and hole near5 (filled or filling) near5 (lacquer or insulating or insulator or dielectric or resin)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/26 17:40
S12	826	(printed circuit or circuit board or pcb or wiring board or printed board) and (etched or etching or etchant) and substrate same3 hole near5 (plated or plating or electroless or electroplating or electroplated) and hole near5 (filled or filling) near5 (lacquer or insulating or insulator or dielectric or resin)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/26 17:41

S13	976	(printed circuit or circuit board or pcb or wiring board or printed board) and (etched or etching or etchant) and substrate and hole near5 (plated or plating or electroless or electroplating or electroplated) and hole near5 (filled or filling) near5 (lacquer or insulating or insulator or dielectric or resin)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/26 17:41
S14	639	(printed circuit or circuit board or pcb or wiring board or printed board).ti,ab,clm. and (etched or etching or etchant) and substrate and hole near5 (plated or plating or electroless or electroplating or electroplated) and hole near5 (filled or filling) near5 (lacquer or insulating or insulator or dielectric or resin)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/26 17:42
S15	871	(printed circuit or circuit board or pcb or wiring board or printed board) and (etched or etching or etchant) with (metal or conductive or plated or copper) and substrate and hole near5 (plated or plating or electroless or electroplating or electroplated) and hole near5 (filled or filling) near5 (lacquer or insulating or insulator or dielectric or resin)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/26 17:43
S16	1002	(printed circuit or circuit board or pcb or wiring board or printed board) and (etched or etching or etchant) with (metal or conductive or plated or copper) and hole near5 (plated or plating or electroless or electroplating or electroplated) and hole near5 (filled or filling) near5 (lacquer or insulating or insulator or dielectric or resin)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/26 17:45
S17	724	(printed circuit or circuit board or pcb or wiring board or printed board) and (etched or etching or etchant) with (metal or conductive or plated or copper) and hole near5 (plated or plating or electroless or electroplating or electroplated) and hole near5 (filled or filling) near5 (lacquer or insulating or insulator or dielectric or resin) and substrate with hole	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/26 17:47
S18	529	S17 and (solder mask or insulating or non-conductive) with (board or substrate)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/26 18:09
S19	597	S17 and (covered or coated or applied or deposited) with (board or substrate)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/26 18:09

S20	261	S17 and (solder mask or insulating or non-conductive) with (board or substrate) with (covered or coated or applied or deposited)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/26 18:10
S21	1	("6407345").PN.	US-PGPUB; USPAT	OR	OFF	2008/09/26 18:51

9/ 29/ 2008 3:02:11 PM

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